C0603X132KATAC7411

SMD Comm X8G HT150C Flex, Ceramic, 1,300 pF, 10%, 250 VDC, X8G,
SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm

Click here for the 3D model.

General Information

Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.85mm +/-0.07mm
S	0.4mm MIN
B	0.45mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	10000

Specifications

Capacitance	1,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms